Abstract of the Disclosure

On the surface of a back board 30 are provided outermost-layer signal lines 6a, 6b, each having a length different form each other on the basis of the difference in length between connector lines 3a, 3b, and these outermost-layer signal lines are connected with the connector lines 3a, 3b, respectively. A digital signal "a" generated in the circuit of a daughter board 10 reaches a through hole 2a through an internal-layer signal line 1a traced within the internal layer of the daughter board 10, and is further transmitted to an internal-layer signal line 5a of the back board 30 through the connector line 3a, the outermost-layer signal line 6a, and a through hole 4a. The digital signal "a" is further transmitted to an internal-layer signal line 1a' via a through hole 4a', a connector line 3a', and a through hole 2a'.